



PATENT

Docket No. 20059/PIA31205

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicant(s):

OH, Sang Jun

U.S. Serial No.: 10/764,905

For: "Methods for Forming an Air Gap in a Semiconductor Metal Line Manufacturing Process"

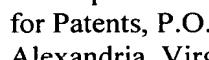
Filed: January 26, 2004

Group Art Unit: 1756

Examiner: Not yet Assigned

I hereby certify that this paper and the documents referred to as enclosed therewith are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on this date:

June 8, 2005


James A. Flight
Attorney for Applicant(s)
Registration No. 37,622

STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Kindly advise when an Office action can be expected in the above-referenced matter.

Respectfully submitted,

HANLEY, FLIGHT & ZIMMERMAN, LLC
USPTO Customer Number 34431
20 North Wacker Drive
Suite 4220
Chicago, Illinois 60606
(312) 580-1020

June 8, 2005

By:

James A. Flight
Registration No.: 37,622